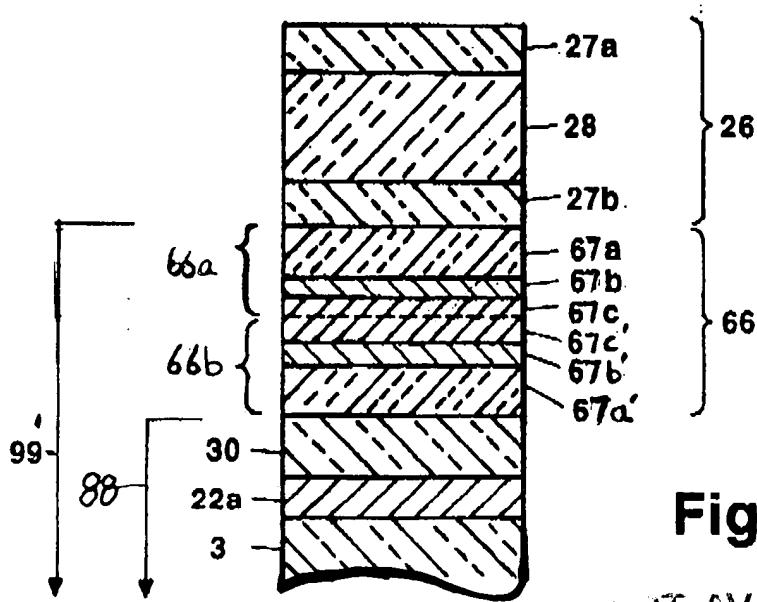
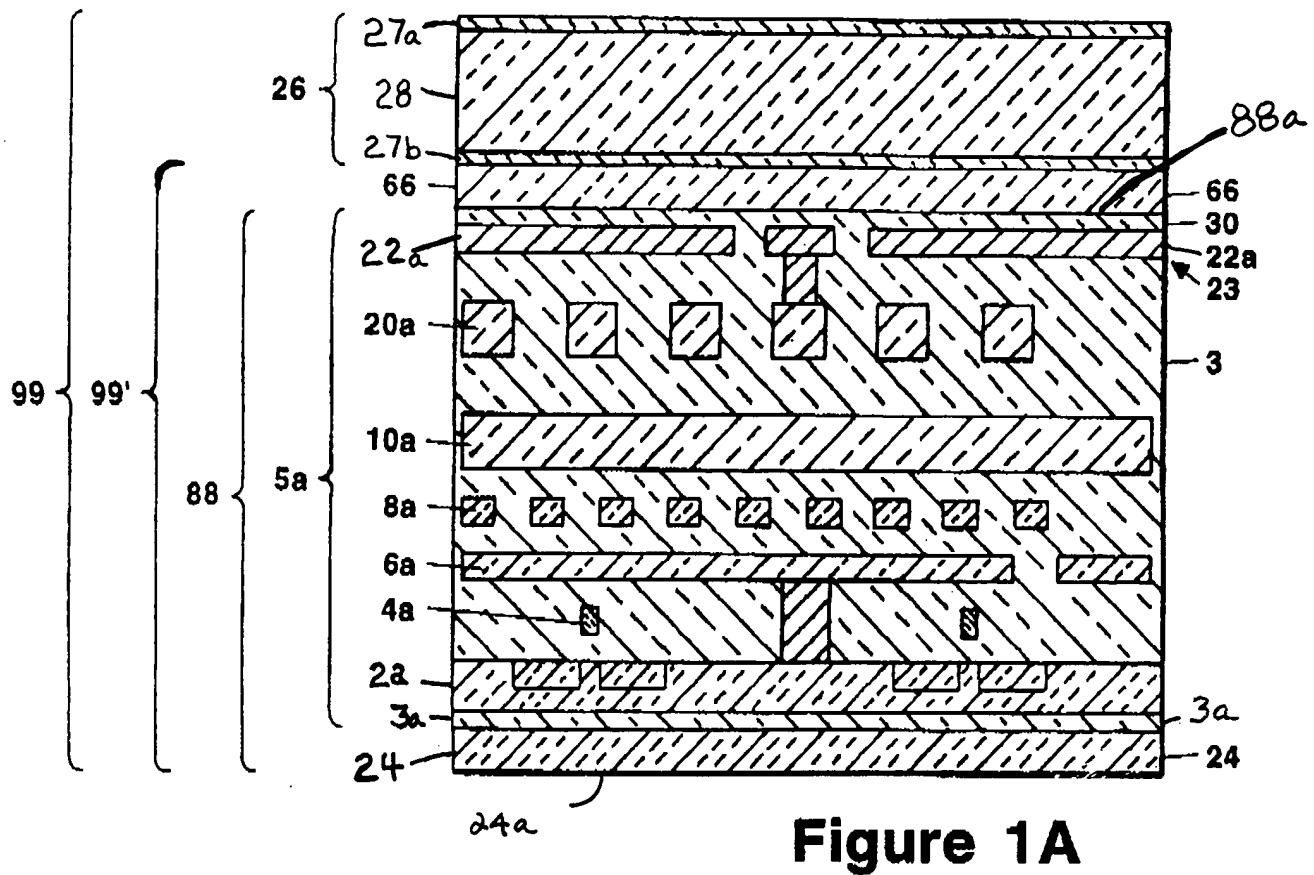


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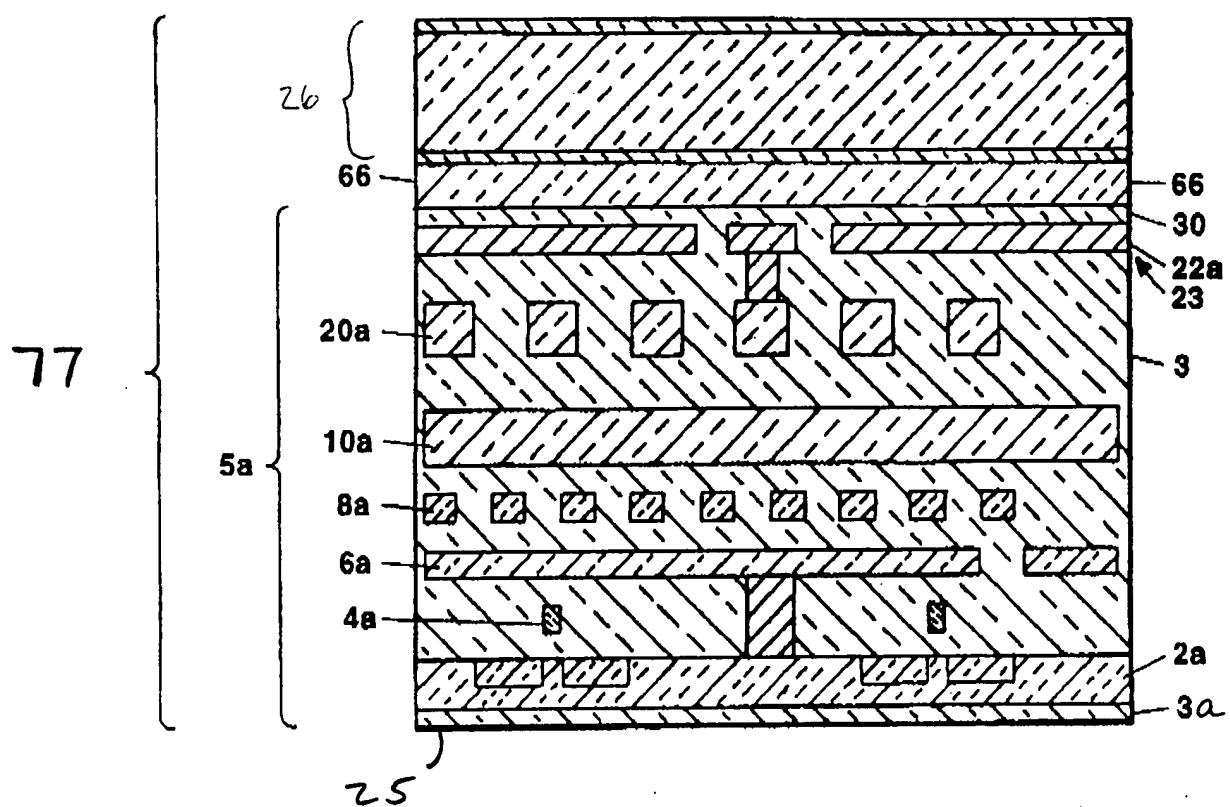


Figure 2A

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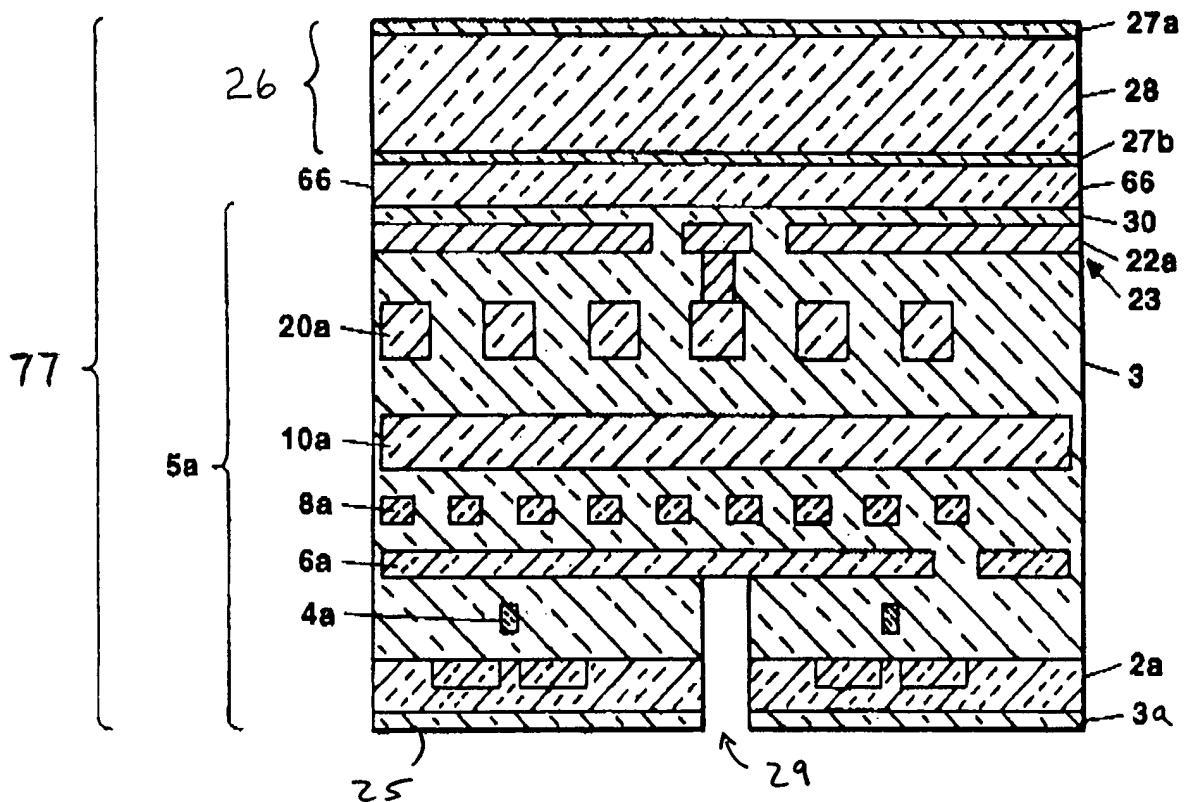


Figure 2B

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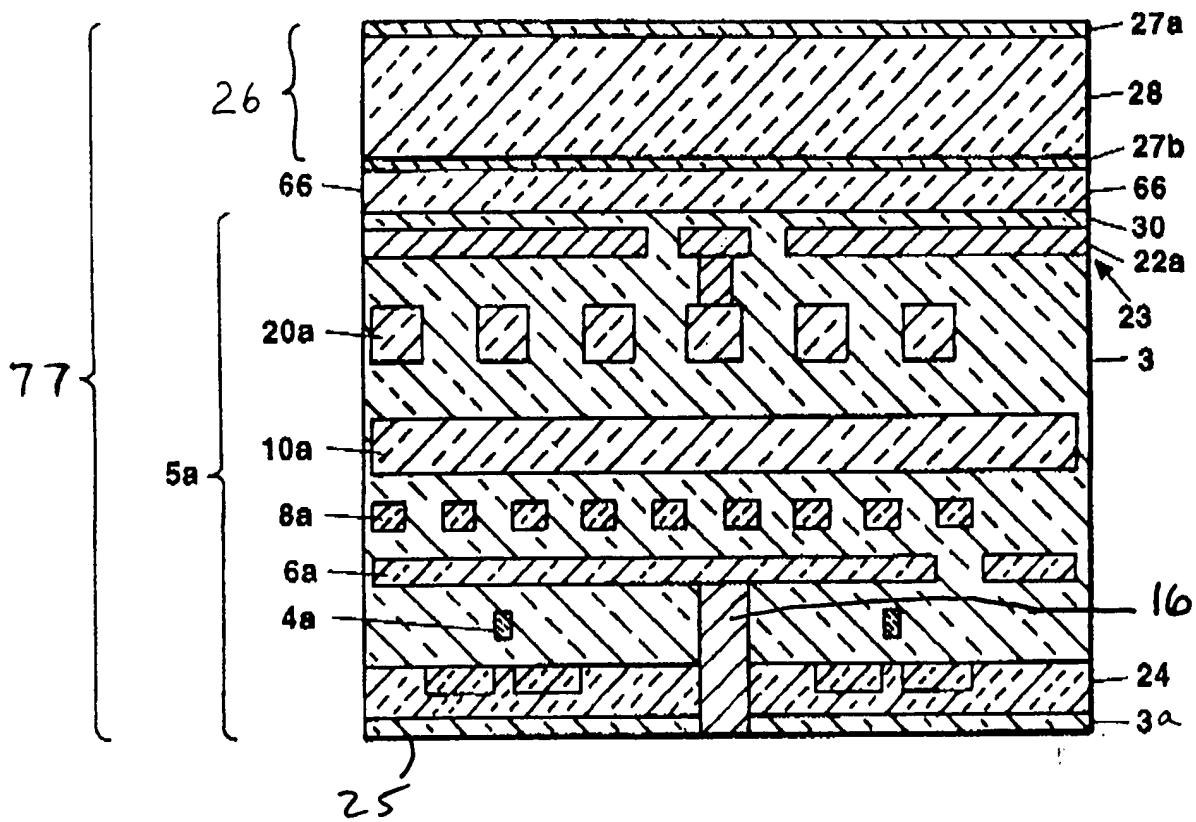
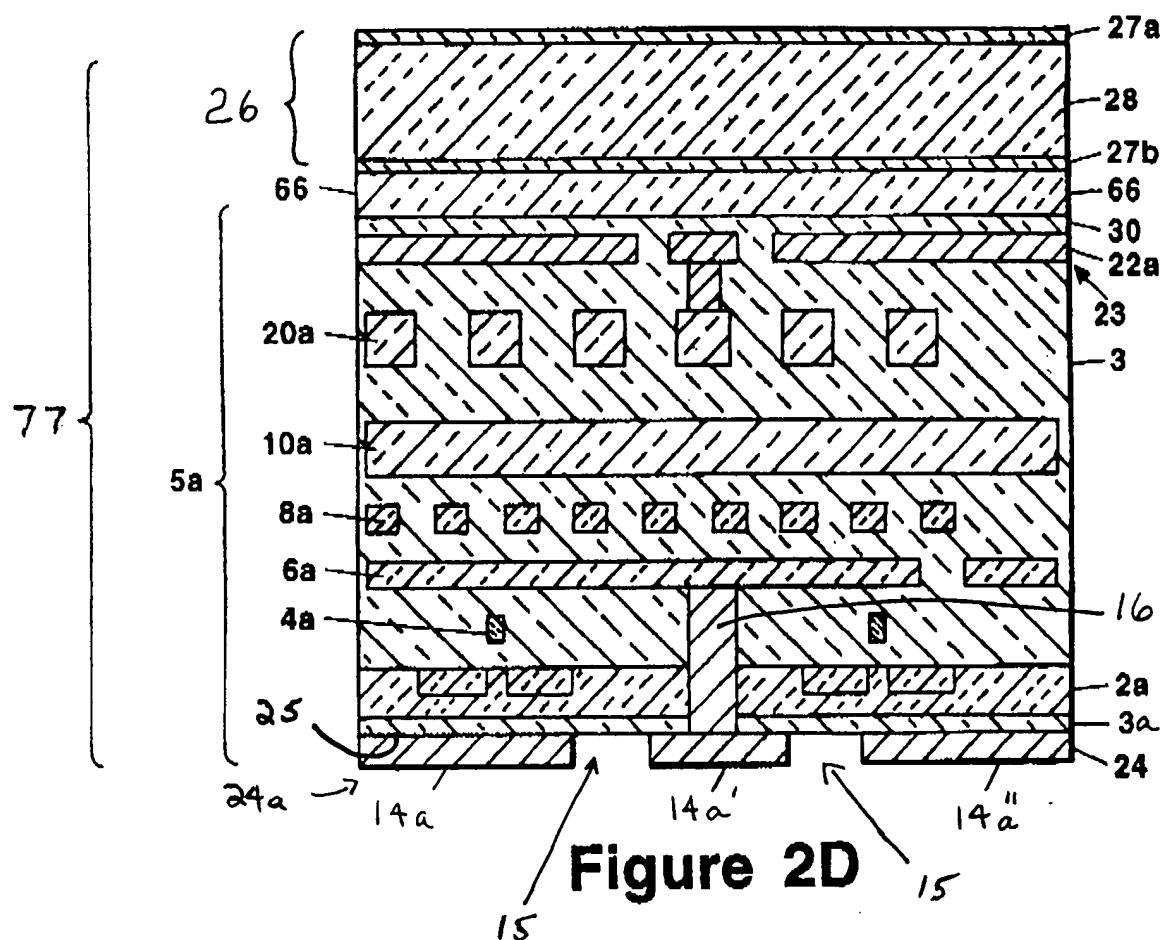


Figure 2C

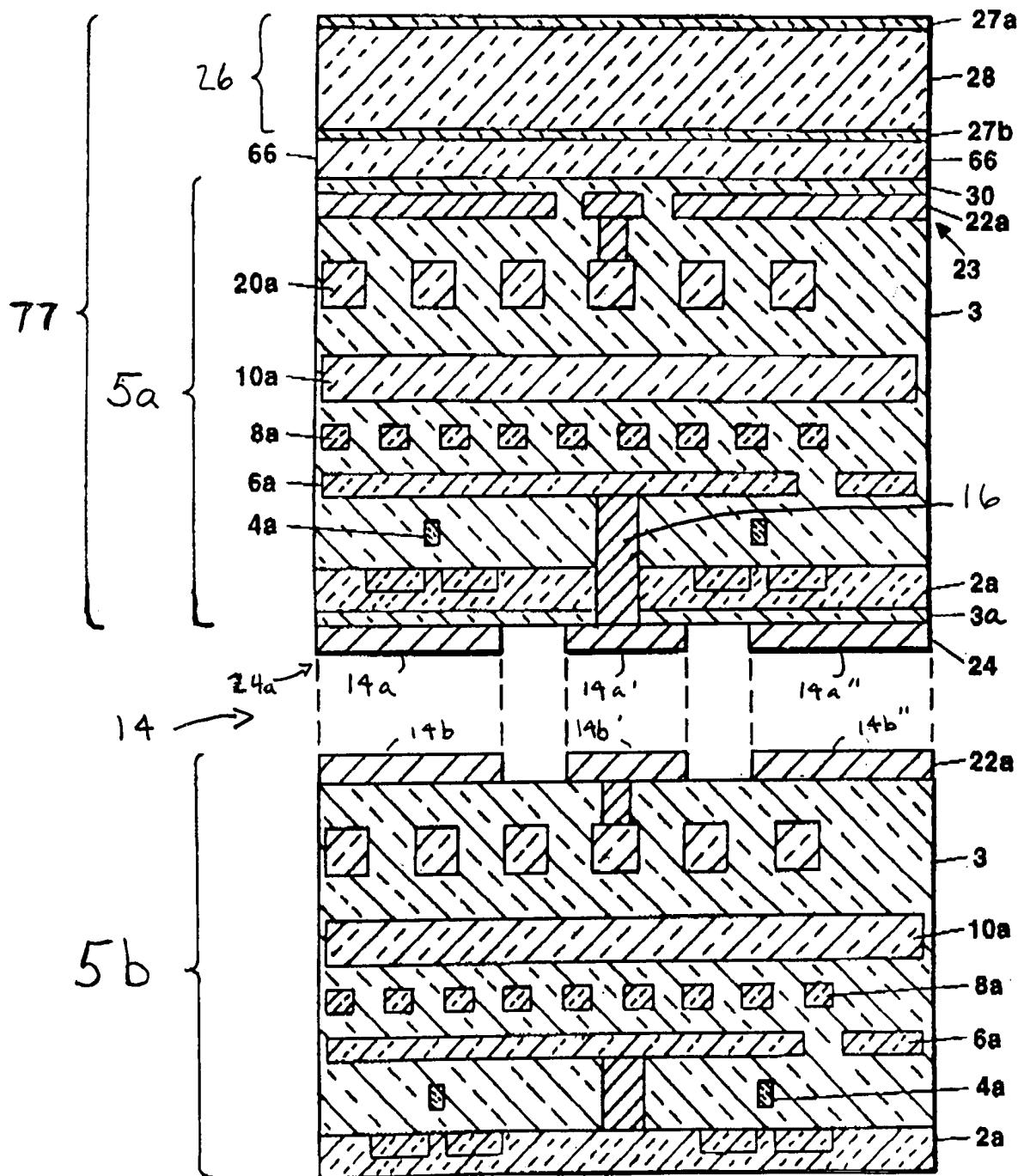
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Figure 3A

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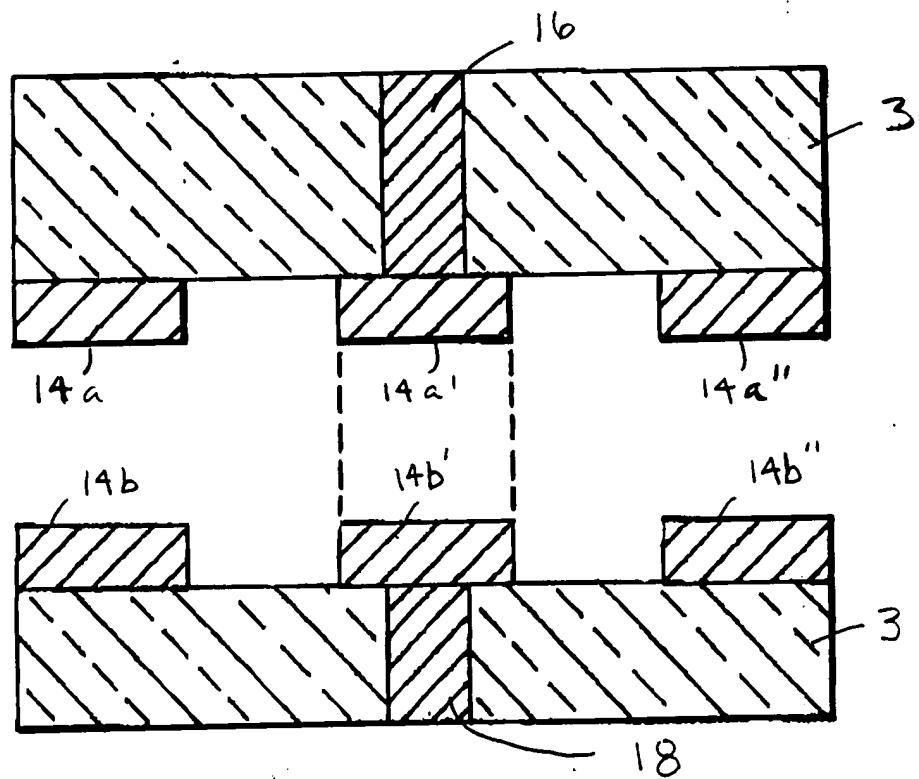


Figure 3B

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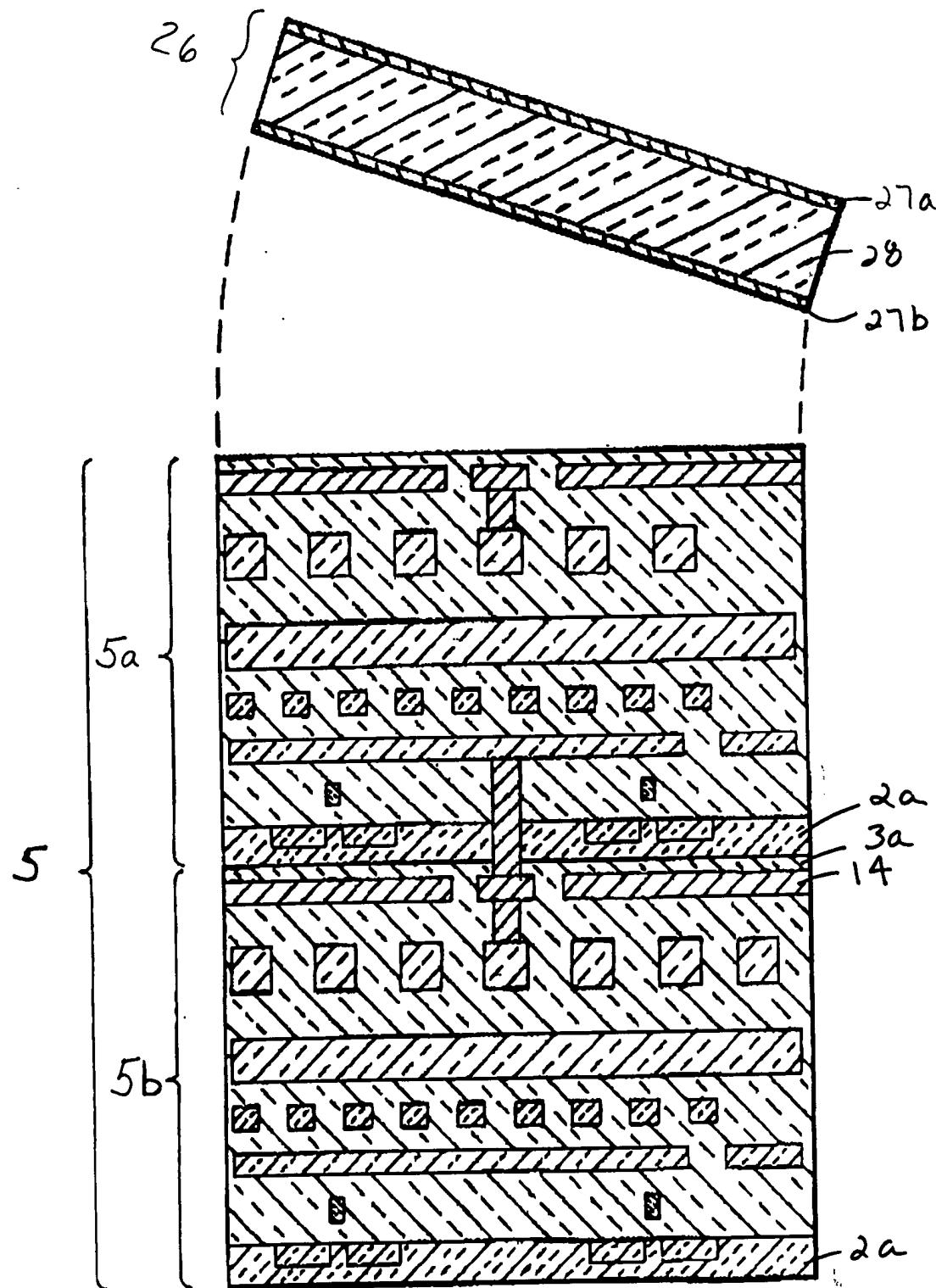


Figure 4A

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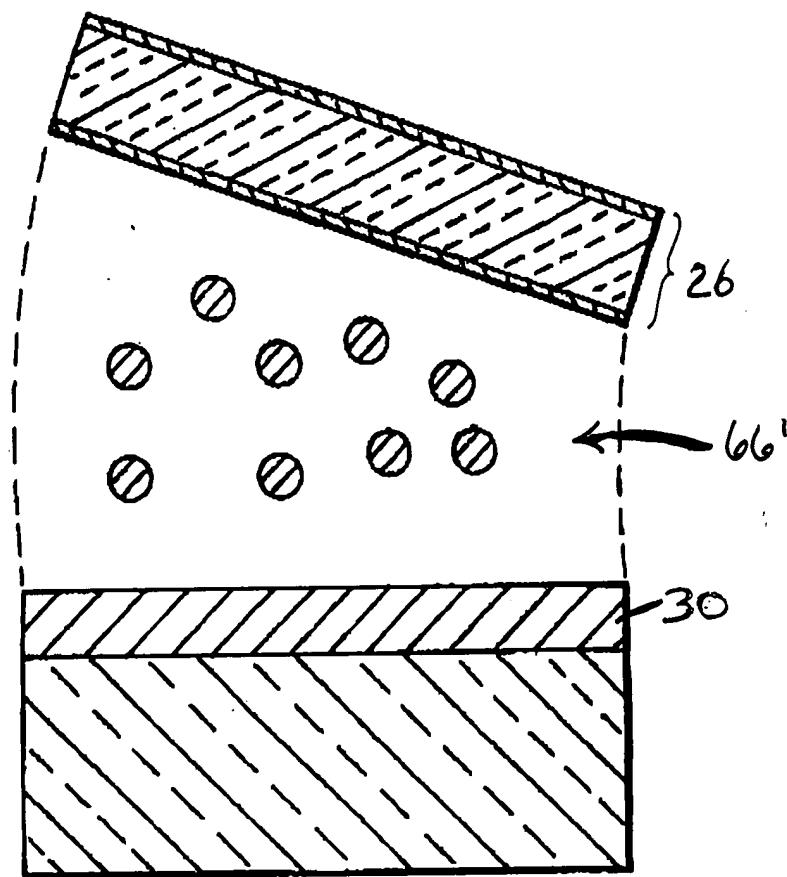


Figure 4B

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